Precision 3560

Technical Guidebook



Notes, cautions, and warnings

(i) NOTE: A NOTE indicates important information that helps you make better use of your product.

CAUTION: A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

MARNING: A WARNING indicates a potential for property damage, personal injury, or death.

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Views of Precision 3560

Right view



- 1. micro-SD card slot
- 3. USB 3.2 Gen 1 port
- 5. HDMI 2.0 port
- 7. Wedge-shaped lock slot

- 2. Universal audio port
- 4. USB 3.2 Gen 1 port with PowerShare
- 6. RJ-45 Ethernet port

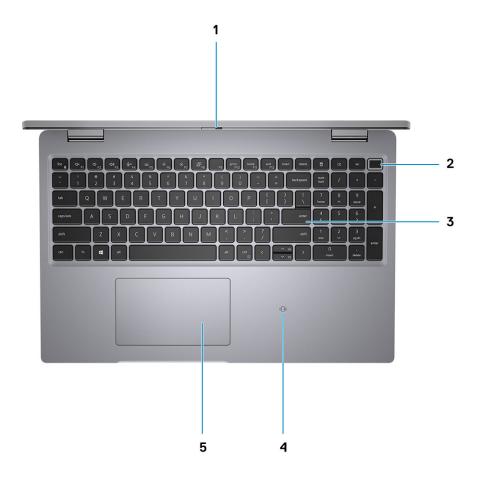
Left view



- 1. Thunderbolt 4 port with DisplayPort Alt Mode/USB4/Power 2. Thunderbolt 4 port with DisplayPort Alt Mode/USB4/Power Delivery
- 3. Air vents

- Delivery
- 4. Smart card reader slot (optional)

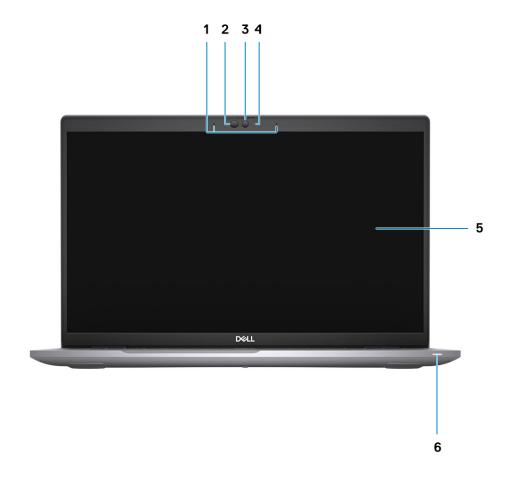
Palm-rest view



- 1. Privacy shutter
- 3. Keyboard
- 5. Clickpad

- 2. Power button with fingerprint reader—(optional)
- 4. NFC/Contactless smart card reader—(optional)

Display view



- 1. Dual-array microphones
- 3. Camera (IR/RGB)
- 5. Display panel

- 2. IR emitter/Ambient Light Sensor (ALS)—(optional)
- 4. Camera status LED
- 6. Battery indicator LED

Bottom view



- 1. Speakers
- 3. Service tag label

- 2. microSIM-card slot (optional)
- 4. Air vent

Keyboard shortcuts

NOTE: Keyboard characters may differ depending on the keyboard language configuration. Keys that are used for shortcuts remain the same across all language configurations.

Table 1. List of keyboard shortcuts

Keys	Primary Behavior	Secondary Behavior (Fn + Key)
Fn + Esc	Escape	Toggle Fn-key lock
Fn + F1	Mute audio	F1 behavior
Fn + F2	Decrease volume	F2 behavior
Fn + F3	Increase volume	F3 behavior
Fn + F4	Mic Mute	F4 behavior
Fn + F5	Keyboard backlight	F5 behavior

Table 1. List of keyboard shortcuts (continued)

Keys	Primary Behavior	Secondary Behavior (Fn + Key)
	(i) NOTE: Not applicable for non-backlight keyboard.	
Fn + F6	Decrease screen brightness	F6 behavior
Fn + F7	Increase screen brightness	F7 behavior
Fn + F8	Switch to external display	F8 behavior
Fn + F9	Disable camera	F9 behavior
Fn + F10	Print Screen	F10 behavior
Fn + F11	Home	F11 behavior
Fn + F12	End	F12 behavior
Fn + Right Ctrl	Emulates right click	

Battery Charge and Status LED

Table 2. Battery Charge and Status LED Indicator

Power Source	LED Behavior	System Power State	Battery Charge Level
AC Adapter	Off	S0 - S5	Fully Charged
AC Adapter	Solid White	S0 - S5	< Fully Charged
Battery	Off	S0 - S5	11-100%
Battery	Solid Amber (590+/-3 nm)	S0 - S5	< 10%

- S0 (ON) System is turned on.
- S4 (Hibernate) The system consumes the least power compared to all other sleep states. The system is almost at an OFF state, expect for a trickle power. The context data is written to hard drive.
- S5 (OFF) The system is in a shutdown state.

Specifications of Precision 3560

Dimensions and weight

Table 3. Dimensions and weight

D	escription	Values
Height:		
	Front	0.78 in. (19.87 mm)
	Rear	0.87 in. (22.15 mm)
W	lidth	14.08 in. (357.80 mm)
D	epth	9.29 in. (236.20 mm)
W	eight (Minimum)	3.50 lb (1.59 kg)

Processors

Table 4. Processors

Description	Values			
Processors	11 th Generation Intel Core i5-1135G7	11 th Generation Intel Core i5-1145G7	11 th Generation Intel Core i7-1165G7	11 th Generation Intel Core i7-1185G7
Wattage	17.50 W	17.50 W	17.50 W	17.50 W
Core count	4	4	4	4
Thread count	8	8	8	8
Speed	2.40 GHz to 4.20 GHz	2.60 GHz to 4.40 GHz	2.80 GHz to 4.70 GHz	3 GHz to 4.80 GHz
Cache	8 MB	8 MB	12 MB	12 MB
Integrated graphics	Intel Iris X ^e Graphics (i) NOTE: System with single-channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC)	Intel Iris Xe Graphics (i) NOTE: System with single-channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC)	Intel Iris X ^e Graphics (i) NOTE: System with single-channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC)	Intel Iris X ^e Graphics (i) NOTE: System with single-channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC)

Chipset

Table 5. Chipset

Description	Values
Chipset	Intel PCH-LP
Processor	11th Generation Intel Core i5/i7 processors
DRAM bus width	64-bit
Flash EPROM	32 MB
PCle bus	Upto Gen 4

Operating system

- Windows 10 Pro, 64-bit
- Windows 10 Home, 64-bit
- Ubuntu Linux 20.04 LTS, 64-bit

Memory

Table 6. Memory specifications

Description	Values	
Slots	Two SO-DIMM slots	
Туре	DDR4, Dual-channel	
Speed	3200 MHz	
Maximum memory	64 GB	
Minimum memory	4 GB	
Configurations supported	 4 GB, 1 x 4 GB, DDR4, 3200 MHz 8 GB, 2 x 4 GB, DDR4, 3200 MHz 8 GB, 1 x 8 GB, DDR4, 3200 MHz 16 GB, 2 x 8 GB, DDR4, 3200 MHz 16 GB, 1 x 16 GB, DDR4, 3200 MHz 32 GB, 2 x 16 GB, DDR4, 3200 MHz 64 GB, 2 x 32 GB, DDR4, 3200 MHz 	

Ports and connectors

Table 7. External ports and connectors

Description	Values
Network	One RJ-45 port
USB	One USB 3.2 Gen 1 port

Table 7. External ports and connectors (continued)

Description	Values
	 One USB 3.2 Gen 1 port with PowerShare Two Thunderbolt 4 ports with DisplayPort Alt Mode/ USB4/Power Delivery
Audio	One universal audio port
Video	One HDMI 2.0 port
Power adapter port	USB Type-C power input
Security	One wedge-shaped lock slot
Card slot	 One microSD-card slot One Smart card reader slot (optional) One microSIM-card slot (optional)

Table 8. Internal ports and connectors

Description	Values
Internal:	
M.2	 M.2 2230 slot for WiFi and Bluetooth combo card M.2 3042 for WWAN One M.2 2280 slot for solid-state drive (computer shipped with discrete graphics card) Two M.2 2280 slots for solid-state drive (computer shipped with UMA graphics card) NOTE: To learn more about the features of different types of M.2 cards, see the knowledge base article SLN301626.

Communications

Ethernet

Table 9. Ethernet specifications

Description	Values
Model number	Intel I219-LMIntel I219-V
Transfer rate	10/100/1000 Mbps

Wireless module

Table 10. Wireless module specifications

Description	Values		
Model number	Intel Wi-Fi 6 AX201	Intel AX210	Qualcomm QCA61x4A
Transfer rate	Up to 2400 Mbps	Up to 2400 Mbps	Up to 867 Mbps

Table 10. Wireless module specifications (continued)

Description	Values		
Frequency bands supported	2.4 GHz/5 GHz	2.4 GHz/5 GHz/6 GHz	2.4 GHz/5 GHz
Wireless standards	 Wi-Fi 802.11a/b/g Wi-Fi 4 (WiFi 802.11n) Wi-Fi 5 (WiFi 802.11ac) Wi-Fi 6 (WiFi 802.11ax) 	 Wi-Fi 802.11a/b/g Wi-Fi 4 (WiFi 802.11n) Wi-Fi 5 (WiFi 802.11ac) Wi-Fi 6 (WiFi 802.11ax) 	 Wi-Fi 802.11a/b/g Wi-Fi 4 (WiFi 802.11n) Wi-Fi 5 (WiFi 802.11ac)
Encryption	64-bit/128-bit WEPAES-CCMPTKIP	64-bit/128-bit WEP AES-CCMP TKIP	64-bit/128-bit WEPAES-CCMPTKIP
Bluetooth	Bluetooth 5.1	Bluetooth 5.2	Bluetooth 5.0

WWAN module

Table 11. Wireless module specifications

Description	Values
Model number	Intel XMM 7360 Global LTE-Advanced, CAT9
Transfer rate	Up to 450 Mbps DL/50 Mbps UL (Cat 9)
Frequency bands supported	(1,2,3,4,5,7,8,11,12,13,17,18,19,20,21,26,28,29,30,38,39,40,41,66), HSPA+ (1, 2, 4,5, 8)
Wireless standards	Not Applicable
Encryption	Not Applicable
Bluetooth	Not Applicable

Audio

Table 12. Audio specifications

Description		Values
Controller		REALTEK ALC3204
Stereo conversion		Supported
Internal interface		High definition audio interface
External interface		Universal audio port
Speakers		Two
Internal speaker amplifier		Supported (audio codec integrated)
External volume controls		Keyboard shortcut controls
Speaker output:		
	Average speaker output	2 W

Table 12. Audio specifications (continued)

Description		Values
	Peak speaker output	2.5 W
Subwoofer output		Not supported
Microphone		Dual-array microphones

Storage

Your computer supports one of the following configurations:

- One M.2 2230, Gen 3 PCle x4 NVMe, Class 35 SSD (slot 1)
- One M.2 2230, Gen 3 PCle x4 NVMe, Class 35 SSD (slot 1) with one M.2 2280, Gen 4 PCle x4 NVMe, Class 40 SSD (slot 2)
- One M.2 2280, Gen 3 PCIe x4 NVMe, Classs 40 SSD (slot 1)
- One M.2 2280, Gen 3 PCle x4 NVMe, Classs 40 SSD (slot 1) with M.2 2280, Gen 4 PCle x4 NVMe, Class 40 SSD (slot 2)
- One M.2 2280, Gen 4 PCle x4 NVMe, Class 40 SSD (slot 2)
- One M.2 2280, Gen 3 PCle x4 NVMe, Class 40 SSD, Self-encrypting drive (slot 1)
- One M.2 2280, Gen 3 PCle x4 NVMe, Class 40 SSD, Self-encrypting drive (slot 1) with one M.2 2280, Gen 4 PCle x4 NVMe, Class 40 SSD (slot 2)

The primary drive of your computer varies with the storage configuration.

Table 13. Storage specifications

Form factor	Interface type	Capacity
M.2 2230, Class 35 solid-state drive	Gen 3 PCle x4 NVMe	Up to 512 GB
M.2 2280, Class 40 solid-state drive	Gen 3 PCle x4 NVMe	Up to 1 TB
M.2 2280, Class 40 solid-state drive	Gen 4 PCle x4 NVMe	2 TB
M.2 2280, Class 40 solid-state drive, Self-encrypting drive	Gen 3 PCle x4 NVMe	Up to 512

Media-card reader

Table 14. Media-card reader specifications

Description	Values
Туре	One microSD-card
Cards supported	 Secure Digital (SD 4.0) Secure Digital High Capacity (SDHC) Secure Digital Extended Capacity (SDXC)

Keyboard

Table 15. Keyboard specifications

Description	Values
Туре	 US/UK/JP layout, single point, non-backlit keyboard US/UK/JP layout, single point, backlit keyboard

Table 15. Keyboard specifications (continued)

Description	Values	
Layout	QWERTY	
Number of keys	United States and Canada: 79 keysUnited Kingdom: 80 keysJapan: 83 keys	
Size	X=18.05 mm key pitch Y=18.05 mm key pitch	
Shortcut keys	Some keys on your keyboard have two symbols on them. These keys can be used to type alternate characters or to perform secondary functions. To type the alternate character press Shift and the desired key. To perform secondary functions, press Fn and the desired key.	
	NOTE: You can define the primary behavior of the function keys (F1–F12) by changing the Function Key Behavior in system setup program. Keyboard shortcuts	

Camera

Table 16. Camera specifications

Desc	cription	Values
Num	ber of cameras	Two
Туре		FHD RGB Infrared camera or HD RGB Infrared camera
Loca	ation	Front camera
Sens	sor type	CMOS sensor technology
Resc	plution	
	Camera	
	Still image	0.92 megapixel
	Video	1280 x 720 (HD/FHD) at 30 fps
	Infrared camera	
	Still image	0.23 megapixel
	Video	640 x 480 (VGA) at 30 fps
Diag	onal viewing angle	
	Camera	FHD: 87.6 degreesHD: 87 degrees
	Infrared camera	FHD: 87.6 degreesHD: 87 degrees

Clickpad

Table 17. Clickpad specifications

Description		Values
Resolution		>=300 dpi
Dimensions:		
	Horizontal	115 mm (4.53 inch)
	Vertical	67 mm (2.64 inch)

Power adapter

Table 18. Power adapter specifications

Des	scription		Values				
Тур	е	65 W AC adapter, USB-C	90 W AC adapter, USB-C	130 W AC adapter, USB-C			
Inpu	ut voltage	100 VAC x 240 VAC	100 VAC x 240 VAC	100 VAC x 240 VAC			
Inpu	ut frequency	50 Hz to 60 Hz	50 Hz to 60 Hz	50 Hz to 60 Hz			
Inpu	ut current (maximum)	1.7 A	1.5 A	1.8 A			
Output current (continuous)		 20 V/3.25 A (Continuous) 15 V/3 A (Continuous) 9.0 V/3 A (Continuous) 5.0 V/3 A (Continuous) 	 20 V/4.5 A (Continuous) 15 V/3 A (Continuous) 9.0 V/3 A (Continuous) 5.0 V/3 A (Continuous) 	20 V/6.5 A (Continuous)5.0 V/1 A (Continuous)			
Rated output voltage		20 VDC/15 VDC/9 VDC/5 VDC	20 VDC/15 VDC/9 VDC/5 VDC	20 VDC/5 VDC			
Ten	nperature range:	·					
	Operating	0°C to 40°C (32°F to 104°F)	0°C to 40°C (32°F to 104°F)	0°C to 40°C (32°F to 104°F)			
	Storage	-40°C to 70°C (-40°F to 158°F)	-40°C to 70°C (-40°F to 158°F)	-40°C to 70°C (-40°F to 158°F)			

Battery

NOTE: Dell recommends that you charge the battery regularly for optimal power consumption. If your battery charge is completely depleted, connect the power adapter, turn on your computer, and then restart your computer to reduce the power consumption.

Table 19. Battery specifications

Description	Values				
Туре	3-cell lithium-ion, 42 WHr, ExpressChargeBoost	3-cell lithium-ion 42 WHr, LCL	4-cell lithium-ion, 63 WHr, ExpressChargeBoos t	4-cell lithium-ion 63 WHr, LCL	

Table 19. Battery specifications (continued)

Descrip	ption		Values		
Voltage		11.40 VDC	11.40 VDC	15.20 VDC	15.20 VDC
Weight (maximum)		0.18 kg (0.40 lb)	0.18 kg (0.40 lb)	0.25 kg (0.55 lb)	0.25 kg (0.55 lb)
Dimensi	ions:				
	Height	5.70 mm (0.22 in.)	5.70 mm (0.22 in.)	5.70 mm (0.22 in.)	5.70 mm (0.22 in.)
	Width	95.90 mm (3.78 in.)	95.90 mm (3.78 in.)	95.90 mm (3.78 in.)	95.90 mm (3.78 in.)
	Depth	207.90 mm (8.19 in.)	207.90 mm (8.19 in.)	238.00 mm (9.37 in.)	238.00 mm (9.37 in.)
Temper range:	rature				
	Operating	 Charge: 0°C to 50°C (32°F to 122°F) Discharge:0°C to 70°C (32°F to 158°F) 	 Charge: 0°C to 50°C (32°F to 122°F) Discharge:0°C to 70°C (32°F to 158°F) 	 Charge: 0°C to 50°C (32°F to 122°F) Discharge:0°C to 70°C (32°F to 158°F) 	 Charge: 0°C to 50°C (32°F to 122°F) Discharge:0°C to 70°C (32°F to 158°F)
	Storage	-20°C to 60°C (-4°F to 140°F)	-20°C to 60°C (-4°F to 140°F)	-20°C to 60°C (-4°F to 140°F)	-20°C to 60°C (-4°F to 140°F)
Operating time		Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.	Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.	Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.	Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.
Chargin (approx	•	From 0% up to 35% in 20 minutes (ExpressCharge Boost), 2hr (Express charge), 3hr (Standard charge) hours (when the computer is off) i NOTE: Control the charging time, duration, start and end time, and so on using the Dell Power Manager application.	2hr (Express charge), 3hr (Standard charge) hours (when the computer is off) i NOTE: Control the charging time, duration, start and end time, and so on using the Dell Power Manager application.	From 0% up to 35% in 20 minutes (ExpressCharge Boost), 2hr (Express charge), 3hr (Standard charge) hours (when the computer is off) i NOTE: Control the charging time, duration, start and end time, and so on using the Dell Power Manager application.	2hr (Express charge), 3hr (Standard charge) hours (when the computer is off) i NOTE: Control the charging time, duration, start and end time, and so on using the Dell Power Manager application.
Life span (approximate)		1 year	1 year	3 years	3 years
Coin-ce	ell battery	CR-2032	CR-2032	CR-2032	CR-2032
Operating time		Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.	Varies depending on operating conditions and can significantly reduce under certain	Varies depending on operating conditions and can significantly reduce under certain	Varies depending on operating conditions and can significantly reduce under certain power-intensive conditions.

Table 19. Battery specifications (continued)

Description	Values			
		'	power-intensive conditions.	

Display

Table 20. Display specifications

Description	Values				
Туре	High Definition (HD)	Full High Definition (FHD)	Full High Definition (FHD)	Full High Definition (FHD)	Ultra High Definition (UHD)
Panel technology	TFT, TN (Twisted Nematic)	TFT, Wide Viewing Angle (WVA)	TFT, Wide Viewing Angle (WVA)	TFT, Wide Viewing Angle (WVA), Low Blue Light (LBL)	TFT, Wide Viewing Angle (WVA), Low Blue Light (LBL)
Luminance (typical)	220 nits	250 nits	250 nits	400 nits	400 nits
Dimensions				•	1
Height	344.16 mm	344.16 mm	344.16 mm	344.16 mm	344.16 mm
Width	193.59 mm	193.59 mm	193.59 mm	193.59 mm	193.59 mm
Diagonal	396.24 mm	396.24 mm	396.24 mm	396.24 mm	396.24 mm
Native resolution	1366 x 768	1920 x 1080	1920 x 1080	1920 x 1080	3840 x 2160
Megapixels	1.05	2.07	2.07	2.07	8.29
Color gamut	NTSC 45%	NTSC 45%	NTSC 45%	sRGB 100%	sRGB 100%
Pixels per inch (PPI)	100	141	141	141	283
Contrast ratio (min)	500:1	700:1	700:1	700:1	1000:1
Response time (max)	25 ms	25 ms	25 ms	25 ms	19 ms
Refresh rate	60 Hz	60 Hz	60 Hz	60 Hz	60 Hz
Horizontal view angle	40 +/-degrees	80 +/-degrees	80 +/-degrees	80 +/-degrees	80 +/- degrees
Vertical view angle	10 (U) / 30 (D) +/-degrees	80 +/-degrees	80 +/-degrees	80 +/-degrees	80 +/- degrees
Pixel pitch	0.252 mm	0.17925 mm	0.17925 mm	0.17925 mm	0.08964 mm
Power consumption (maximum)	4.2 W	4.6 W	4.5 W	4.5 W	4.5 W

Table 20. Display specifications (continued)

Description	Values				
Anti-reflective vs Anti-smudge	Anti-glare	Anti-glare	Anti-glare	Anti-glare	Anti-glare
Touch options	No	Yes	No	No	No
Stylus support	No	No	No	No	No

Fingerprint reader (optional)

Table 21. Fingerprint reader specifications

Description	Power button option	FIPS option
Sensor technology	Capacitive	Capacitive
Sensor resolution	500 dpi	508 dpi
Sensor pixel size, X	108	256
Sensor pixel size, Y	88	360

Video

Table 22. Discrete graphics specifications

Discrete graphics				
Controller	External display support	Memory size	Memory Type	
NVIDIA T500	NA	2 GB	GDDR6	

Table 23. Integrated graphics specifications

Integrated graphics					
Controller External display support Memory size F		Processor			
Intel Iris X ^e Graphics	HDMI 2.0, DisplayPort over USB Type-C	Shared system memory	11th Generation Intel Core i5/i7 processors i NOTE: System with single- channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC).		

Security

Table 24. Hardware Security

Hardware security options
Trusted Platform Module (TPM) 2.0 discrete

Table 24. Hardware Security (continued)

Hardware security options

FIPS 140-2 certification for TPM

TCG (Trusted Computing Group) Certification for TPM

Fingerprint reader in power button tied to ControlVault 3

ControlVault 3 Advanced Authentication with FIPS 140-2 Level 3 Certification

Contacted Smart Card and ControlVault 3

Contactless Smart Card, NFC, and ControlVault 3

SED SSD NVMe, SSD and HDD (Opal and non-Opal) per SDL

FIPS 201 Full Scan FPR and ControlVault 3

Table 25. Data Security

Data security options

McAfee Small Business Security 30-day trial

McAfee Small Business Security 12-months subscription, digitally delivered

McAfee Small Business Security 24-months subscription, digitally delivered

McAfee Small Business Security 36-months subscription, digitally delivered

Computer environment

Airborne contaminant level: G1 as defined by ISA-S71.04-1985

Table 26. Computer environment

Description	Operating	Storage
Temperature range	0°C to 40°C (32°F to 104°F)	-40°C to 60°C (-40°F to 140°F)
Relative humidity (maximum)	10% to 90% (non-condensing)	0% to 95% (non-condensing)
Vibration (maximum)*	0.66 GRMS	1.30 GRMS
Shock (maximum)	140 G†	160 G†
Altitude (maximum)	-15.2 m to 3048 m (-50 ft to 10000 ft)	-15.2 m to 10668 m (-50 ft to 35000 ft)

 $^{^{}st}$ Measured using a random vibration spectrum that simulates user environment.

Sensor and control

Table 27. Sensor and control

Sensor support				
Sensor	Ambient Light Sensor on the hinge-up (optional)			
	P-sensor on the hinge-up (optional)			
	Accelerometer (G sensor): One on the base (system board) and another on the hinge-up (optional)			

 $[\]ensuremath{\uparrow}$ Measured using a 2 ms half-sine pulse when the hard drive is in use.

Engineering specifications

Graphics options

Integrated graphics

Table 28. Integrated graphics

Feature	Intel Iris X ^e Graphics i NOTE: System with single-channel memory is shown as Intel UHD Graphics in Intel Graphics Command Center (IGCC)
Bus type	Integrated
Memory type	DDR4
Memory interface	N/A (Unified Memory Architecture)
Estimated Maximum Power Consumption (TDP)	15 W - included in the CPU power
External connectors	HDMI and Type-C DisplayPort alt mode
Multiple display support	Yes (up to 3 displays - including internal panel display)

Communications

Wireless LAN options

Intel Wi-Fi 6 AX201 802.11AX 2x2 Wi-Fi and Bluetooth 5.1

Table 29. Intel AX201 802.11AX 2x2 Wi-Fi and Bluetooth 5.1

Feature	Specifications
Туре	Intel AX201
Network standard	IEEE 802.11a/b/g/n/ac/ax, 160 MHz channel use, MU-MIMO
Wi-Fi Alliance certifications	Wi-Fi CERTIFIED* a/b/g/n/ac with wave 2 features, designed to be Wi-Fi CERTIFIED* ax (Wi-Fi 6), WMM*, WMM-PS*, WPA*, WPA2*, WPS2*, Protected Management Frames, and Wi-Fi Direct (For Microsoft Windows* only)
Transfer rate	Up to 2400 Gbps
Operating Frequency Bands	Dual band 2.4 GHz and 5 GHz
Data Rate	 2.4 GHz 40 M - Up to 574 Mbps 5 GHz 80 M - Up to 1.2 Gbps 5 GHz 160 M - Up to 2 Gbps

Table 29. Intel AX201 802.11AX 2x2 Wi-Fi and Bluetooth 5.1 (continued)

Feature	Specifications
Power consumption	Optimized power modes (sleep states) reduce power consumption during periods of inactivity.
Authentication	WPA* and WPA2* Personal and Enterprise; WPA3* (pending operating system support)
Authentication Protocols	802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 - MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')
Encryption	64-bit and 128-bit WEP, TKIP, 128-bit AES-CCMP, 256-bit AES-GCMP
Government Compliance	FIPS 140-2, FISMA
Client Utility	Intel PRO/Set Wireless Software v21 and later
Antenna Diversity	Supported
Radio On/Off	Supported
Wake On Wireless	Supported
Wireless Display	Native Miracast* support by Windows 10
Wireless PAN Standard	Wi-Fi 802.11ac, Wi-Fi 802.11b/g/n
Bluetooth	5.1
Bluetooth Data rates	Up to 3 Mbps
Bluetooth Operating Frequency Bands	2.4 GHz
Bluetooth Profiles Supported	Support for Microsoft Inbox Bluetooth profiles in Windows 10
Bluetooth Data Encryption	128-bit encryption
Bluetooth Output Power	Power class 1
Temperature	 Operating temperature 0°C to + 50°C (Full performance at shield temperatures up to 80°C) Storage temperature of -40°C to +70°C
Humidity	Up to 90% RH non-condensing (at temperatures of 25°C to 35°C)

Intel Wi-Fi 6 AX210 160 MHz (Typhoon Peak 2) 2x2 Wi-Fi and Bluetooth 5.2 M.2 wireless card

Table 30. Intel Wi-Fi 6 AX210 160 MHz (Typhoon Peak 2) 2x2 Wi-Fi and Bluetooth 5.2 M.2 wireless card

Feature	Specifications
Туре	Intel AX210
Network standard	IEEE 802.11a/b/g/n/ac/ax, 160 MHz channel use, MU-MIMO
Wi-Fi Alliance certifications	Wi-Fi CERTIFIED* a/b/g/n/ac with wave 2 features, designed to be Wi-Fi CERTIFIED* ax (Wi-Fi 6), WMM*, WMM-PS*, WPA*, WPA2*, WPS2*, Protected Management Frames, and Wi-Fi Direct (For Microsoft Windows* only)
Transfer rate	Up to 2400 Gbps
Operating Frequency Bands	2.4 GHz, 5 GHz, and 6 GHz
Data Rate	2.4 GHz 40 M - Up to 574 Mbps5/6 GHz 80 M - Up to 1.2 Gbps

Table 30. Intel Wi-Fi 6 AX210 160 MHz (Typhoon Peak 2) 2x2 Wi-Fi and Bluetooth 5.2 M.2 wireless card (continued)

Feature	Specifications
	• 5/6 GHz 160 M - Up to 2.4 Gbps
Power consumption	Optimized power modes (sleep states) reduce power consumption during periods of inactivity.
Authentication	WPA* and WPA2* Personal and Enterprise; WPA3* (pending operating system support)
Authentication Protocols	802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 - MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')
Encryption	64-bit and 128-bit WEP, TKIP, 128-bit AES-CCMP, 256-bit AES-GCMP
Government Compliance	FIPS 140-2, FISMA
Client Utility	Intel PRO/Set Wireless Software v22 and later
Antenna Diversity	Supported
Radio On/Off	Supported
Roaming	Support seamless roaming between access points
Wake On Wireless	Supported
Wireless Display	Native Miracast* support by Windows 10
Wireless PAN Standard	Dual Mode bluetooth 5.2, BLE
Bluetooth	5.2
Bluetooth Data rates	Up to 3 Mbps
Bluetooth Operating Frequency Bands	2.4 GHz
Bluetooth Profiles Supported	Support for Microsoft Inbox Bluetooth profiles in Windows 10
Bluetooth Data Encryption	128-bit encryption
Bluetooth Output Power	Power class 1
Temperature	 Operating temperature 0°C to + 50°C (Full performance at shield temperatures up to 80°C) Storage temperature of -40°C to +70°C
Humidity	Up to 90% RH non-condensing (at temperatures of 25°C to 35°C)

Dell Qualcomm QCA61x4A, 802.11ac

Table 31. Dell Qualcomm QCA61x4A, DW1820 802.11ac

Feature	Specifications
Host interface	Qualcomm QCA61x4A
Transfer rate	Up to 867 Mbps
Wi-Fi Alliance Certifications	Wi-Fi CERTIFIED* a/b/g/n/ac with wave 2 features, WMM*, WMM-PS*, WPA*, WPA2*, WPS2*, Protected Management Frames, Wi-Fi Miracast* as Source, and Wi-Fi Direct (For Microsoft Windows* only)I
Operating Frequency Bands	Dual band 2.4 GHz/5 GHz
Data Rate	2.4 GHz 40M: Up to 300 Mbps

Table 31. Dell Qualcomm QCA61x4A, DW1820 802.11ac (continued)

Feature	Specifications
	5 GHz 80M: Up to 867 Mbps
	5 GHz 160M: Up to 1.73 Gbps
Power consumption	WPA* and WPA2*, 802.1X (EAP-TLS, TTLS, PEAP, EAP-SIM, EAP-AKA, EAP-AKA')
Authentication	Open, Shared, WPA, WPA-PSK, WPA2, WPA2-PSK
Authentication Protocols	PAP, CHAP, TLS, GTC, MS-CHAP*, MS-CHAP*v2
Encryption	64-bit and 128-bit WEP, TKIP, 128-bit AES-CCMP
Government Compliance	FIPS, FISMA
Client Utility	Intel PRO/Set Wireless Software v20 and later
Antenna Diversity	Supported
Radio On/Off	Supported
Wake On Wireless	Supported
Wireless Display	Native Miracast support by Windows 10
Bluetooth	Bluetooth 5.0
Wireless PAN Standard	Wi-Fi 802.11ac
	Wi-Fi 802.11b/g/n
Bluetooth Data rates	Up to 3 Mbps
Bluetooth Operating Frequency Bands	2.4 GHz
Bluetooth Profiles Supported	Support for Microsoft Inbox Bluetooth profiles in Windows 10
Bluetooth Data Encryption	64/128-bit encryption
Bluetooth Output Power	Power class 1
Temperature	Operating temperature 0 to + 50 C (Full performance at shield temperatures up to 80 C)
	Storage temperature of -40 to +70 C
Humidity	Up to 90% RH non-condensing (at temperatures of 25 C to 35 C)

Wireless WAN options

Intel XMM 7360 Global LTE-Advanced (DW5820e) CAT9, WWAN Module

Feature	Specifications
Host interface	M.2 3042 form factor
Network standard	LTE FDD/TDD, WCDMA/HSPA+, GNSS/Beidou
Transfer rate	Up to 450 Mbps DL/50 Mbps UL (Cat 9)
Operating FrequencyBands	(1,2,3,4,5,7,8,11,12,13,17,18,19,20,21,26,28,29,30,38,39,40,41,66), HSPA+ (1, 2, 4,5, 8)
Data Rate	 LTE FDD: 450 Mbps DL/50 Mbps UL (Cat 9) LTE TDD: 347 Mbps DL/30 Mbps UL (Cat 9) UMTS/HSPA+: UMTS 384 kbps DL/384 kbps UL

Feature	Specifications	
Power supply	DC 3.135 V to 4.4 V, Typical 3.3 V	
SIM card (Micro or Nano)	Supported ¹	
eSIM card (Micro orNano)	Supported ^{1,2}	
Antenna Diversity	Supported	
Radio On/Off	Supported	
Wake On Wireless	Supported	
Temperature	 Normal operating temperature: -10°C to + 55°C Extended Operating temperature: -20°C to +65°C 	
Antenna connector	WWAN Main Antenna x1WWAN Diversity Antenna x1	

(i) NOTE:

- ¹ Use of SIM card is supported through external SIM slot, some model support Nano card only.
- ² The availability of eSIM functionality depends on the region and carrier requirements.

Supported hard drives

M.2 2230 128 GB Gen 3 PCIe x4 NVMe Class 35 Solid-State Drive

Table 32. M.2 2230 128 GB Gen 3 PCIe x4 NVMe Class 35 Solid-State Drive

Features	Specifications
Capacity	128 GB
Dimensions	22.00 mm x 30.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s (Up to 4 lanes)
MTTF	1.4 M hours
Logical blocks	250,069,680
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4) Active: 3.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2230 256 GB Gen 3 PCle x4 NVMe Class 35 Solid-State Drive

Table 33. M.2 2230 256 GB Gen 3 PCIe x4 NVMe Class 35 Solid-State Drive

Features	Specifications
Capacity	256 GB
Dimensions	22.00 mm x 30.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s (Up to 4 lanes)
MTTF	1.4 M hours
Logical blocks	500,118,192
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4) Active: 3.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2230 512 GB Gen 3 PCIe x4 NVMe Class 35 Solid-State Drive

Table 34. M.2 2230 512 GB Gen 3 PCle x4 NVMe Class 35 Solid-State Drive

Features	Specifications
Capacity	512 GB
Dimensions	22.00 mm x 30.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s (Up to 4 lanes)
MTTF	1.4 M hours
Logical blocks	1,000,215,216
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4)Active: 3.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%

Table 34. M.2 2230 512 GB Gen 3 PCle x4 NVMe Class 35 Solid-State Drive (continued)

Features	Specifications
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 256 GB Gen 3 PCle x4 NVMe Class 40 Solid-State Drive

Table 35. M.2 2280 256 GB Gen 3 PCIe x4 NVMe Class 40 Solid-State Drive

Features	Specifications
Capacity	256 GB
Dimensions	22.00 mm x 80.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s
MTTF	1.4 M hours
Logical blocks	500,118,192
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4)Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 512 GB Gen 3 PCIe x4 NVMe Class 40 Solid-State Drive

Table 36. M.2 2280 512 GB Gen 3 PCle x4 NVMe Class 40 Solid-State Drive

Features	Specifications
Capacity	512 GB
Dimensions	22.00 mm x 80.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s
MTTF	1.4 M hours

Table 36. M.2 2280 512 GB Gen 3 PCle x4 NVMe Class 40 Solid-State Drive (continued)

Features	Specifications
Logical blocks	1000,215,216
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4) Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 1 TB Gen 3 PCIe x4 NVMe Class 40 Solid-State Drive

Table 37. M.2 2280 1 TB Gen 3 PCIe x4 NVMe Class 40 Solid-State Drive

eatures Specifications	
Capacity	1 TB
Dimensions	22.00 mm x 80.00 mm x 3.73 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s
MTTF	1.4 M hours
Logical blocks	2000,409,264
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4)Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 2 TB Gen 4 PCle x4 NVMe Class 40 Solid-State Drive

Table 38. M.2 2280 2 TB Gen 4 PCIe x4 NVMe Class 40 Solid-State Drive

Capacity	2 TB
Dimensions	22.00 mm x 80.00 mm x 3.73 mm
Interface type and maximum speed	Gen 4 PCle 32 Gb/s
MTTF	1.4 M hours
Logical blocks	4000,797,360
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4)Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 256 GB Gen 3 PCIe x4 NVMe Opal Self-Encrypting Class 40 Solid-State Drive

Table 39. M.2 2280 256 GB Gen 3 PCle x4 NVMe Opal Self-Encrypting Class 40 Solid-State Drive

Features	Specifications
Capacity	256 GB
Dimensions	22.00 mm x 80.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s (Up to 4 lanes)
MTTF	1.4 M hours
Logical blocks	500,118,192
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4)Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%

Table 39. M.2 2280 256 GB Gen 3 PCIe x4 NVMe Opal Self-Encrypting Class 40 Solid-State Drive (continued)

Features	Specifications
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

M.2 2280 512 GB Gen 3 PCle x4 NVMe Opal Self-Encrypting Class 40 Solid-State Drive

Table 40. M.2 2280 512 GB Gen 3 PCle x4 NVMe Opal Self-Encrypting Class 40 Solid-State Drive

Features	Specifications
Capacity	512 GB
Dimensions	22.00 mm x 80.00 mm x 2.38 mm
Interface type and maximum speed	Gen 3 PCle 32 Gb/s
MTTF	1.4 M hours
Logical blocks	1000,215,216
Power Source	
Power consumption (reference only)	Idle: 5 mW (PS4) Active: 4.5 W
Environmental Operating Conditions (Non-Condensing)	
Temperature range	0°C to 70°C
Relative humidity range	10% to 90%
Non-op shock (@0.5 ms)	1500G
Environmental Non-Operating Conditions (Non-Condensing)	
Temperature range	-40°C to 70°C
Relative humidity range	5% to 95%

Accessories

Table 41. Accessories

Accessories
3Dconnexion SpaceMouse Wireless
Dell Premier Multi-Device Wireless Keyboard and Mouse - KM7321W
Dell Premier Rechargeable Wireless Mouse - MS7421W

Table 41. Accessories (continued)

Accessories

Dell Mobile Adapter Speakerphone - MH3021P

Dell USB-C Mobile Adapter - DA310

Jabra Evolve2 85

Dell Thunderbolt Dock - WD19TB

Dell Notebook Power Bank Plus USB-C, 65 Wh - PW7018LC

Dell Premier Rechargeable Wireless Mouse - MS7421W

Dell Pro Hybrid Briefcase Backpack 15 - PO1521HB

Dell UltraSharp 27 4K Premier Color Monitor - UP2720Q

Dell UltraSharp 27 4K USB-C Monitor - U2720Q

Systems management

Table 42. Systems management

Systems management

Dell Power Manager (DPM) verison 3.0 or later

BIOS complies to Dell SMBIOS implementation spec (DSIS)

SW and Drivers MUP/DUP compliant

Dell Command | Configure (DCC) version 4.0 or later

Dell Command | Monitor (DCM) verison 10.0 or later

Dell Command | Update (DCU) version 3.0 or later

Dell Command | Update Catalog (DCUC)

Dell Command | Deploy (DCP)

Dell Command | Integration Suite for System Center (DCIS) version 5.0

Dell Command | Intel vPro Out of Band (DCIV)

Dell Command | PowerShell Provider version 2.0 or later

Dell Command | Deploy Driver Pack Catalog version 1.0 or later

Getting help

Contacting Dell

Prerequisites

NOTE: If you do not have an active Internet connection, you can find contact information on your purchase invoice, packing slip, bill, or Dell product catalog.

About this task

Dell provides several online and telephone-based support and service options. Availability varies by country and product, and some services may not be available in your area. To contact Dell for sales, technical support, or customer service issues:

Steps

- 1. Go to Dell.com/support.
- 2. Select your support category.
- 3. Verify your country or region in the Choose a Country/Region drop-down list at the bottom of the page.
- 4. Select the appropriate service or support link based on your need.